

Power Inductor

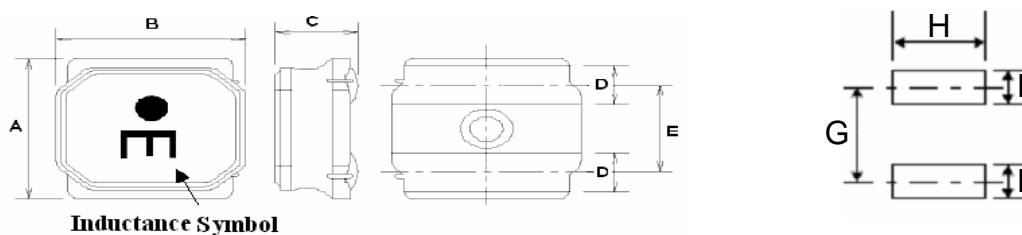
HPC4018B-SERIES

1. Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.



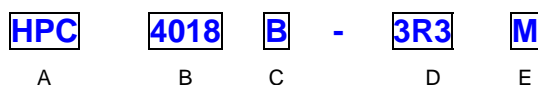
2. Dimension



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	G(mm)	H(mm)	I(mm)
HPC4018B	4.0±0.2	4.0±0.2	1.8 max.	1.1±0.2	2.5±0.2	2.8 ref.	3.7 ref.	1.2 ref.

Units: mm

3. Part Numbering



A: Series

B: Dimension

C: Control S/N

D: Inductance

3R3=3.3uH

E: Inductance Tolerance

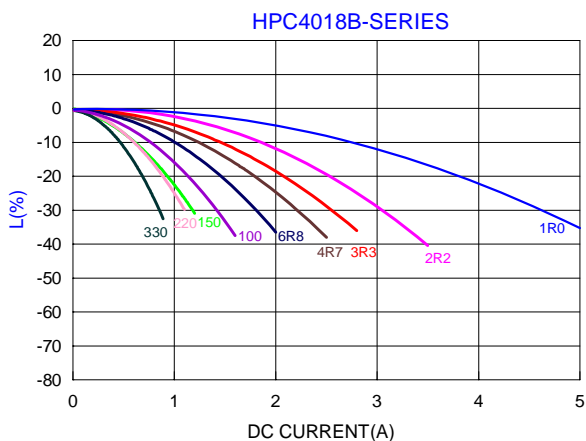
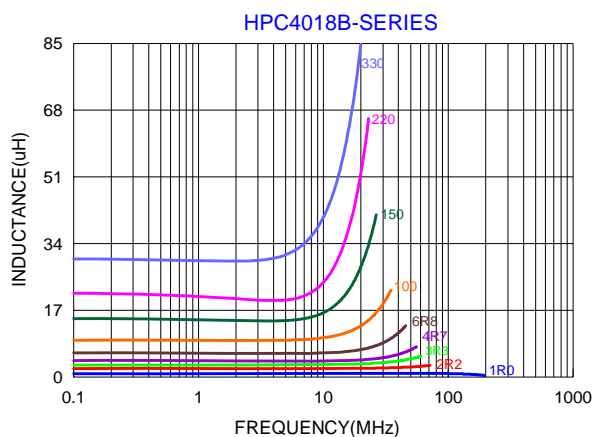
M=±20% ; Y=±30%

4. Specification

TAI-TECH Part Number	Inductance Symbol	Inductance (uH)	Tolerance (%)	Test Frequency (Hz)	SRF (MHz) min.	DCR (Ω) ±20%	I sat (A)	I rms (A)
HPC4018B-1R0Y	A	1.0	±30%	1V100K	90	0.027	4.00	3.20
HPC4018B-2R2M	C	2.2	±20%	1V100K	60	0.042	3.00	2.20
HPC4018B-3R3M	E	3.3	±20%	1V100K	45	0.055	2.30	2.00
HPC4018B-4R7M	H	4.7	±20%	1V100K	35	0.070	2.00	1.70
HPC4018B-6R8M	I	6.8	±20%	1V100K	30	0.098	1.60	1.45
HPC4018B-100M	K	10	±20%	1V100K	25	0.150	1.30	1.20
HPC4018B-150M	M	15	±20%	1V100K	18	0.210	1.10	0.85
HPC4018B-220M	N	22	±20%	1V100K	15	0.290	0.90	0.72
HPC4018B-330M	P	33	±20%	1V100K	12	0.460	0.70	0.55

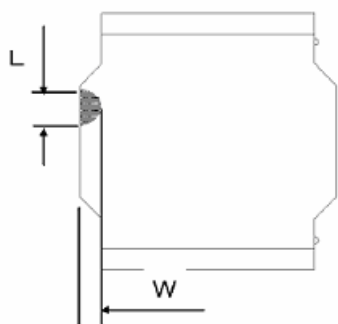
Note:

Isat : Based on inductance change ($\Delta L/L0 : \leq -30\%$) @ ambient temp.Irms : Based on temperature rise ($\Delta T : 40^{\circ}\text{C}$ typ.)



Core chipping

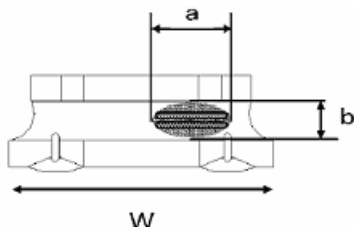
The appearance standard of the chipping size on top side, and bottom side ferrite core is listed below.



Type	L	W
HPC4018B	1.5mm Max.	1.5mm Max.

Void appearance tolerance Limit

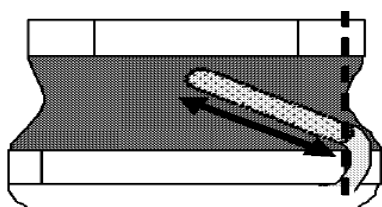
Size of voids occurring to coating resin is specified below.



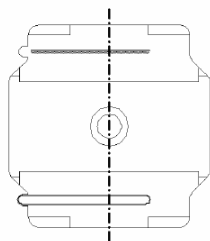
- Exposed wire tolerance limit of coating resin part on product side.
 Size of exposed wire occurring to coating resin is specified below.
1. Width direction (dimension a) : Acceptable when $a \leq w/2$
 Nonconforming when $a > w/2$
 2. Length direction (dimension b) : Dimension b is not specified.
 3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.


External appearance criterion for exposed wire


Exposed end of the winding wire at the secondary side should be 2mm and below.



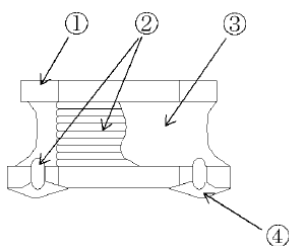
5. Exectrde appearance criterion for exposed wire



 Conforming
 Only top side of wire is exposed.
 (regardless of whole tope side of wire exposed)

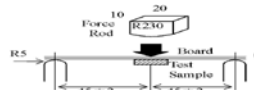
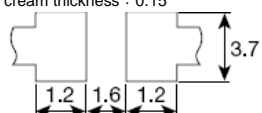
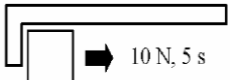
 Less than 1/2 of joint side length.
 (More than 1/2 is selected as defect)
 Wire is soldered insufficiently and less than half of outer diameter is covered with solder.

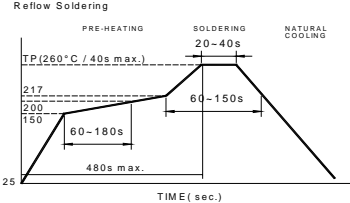
6. Material List



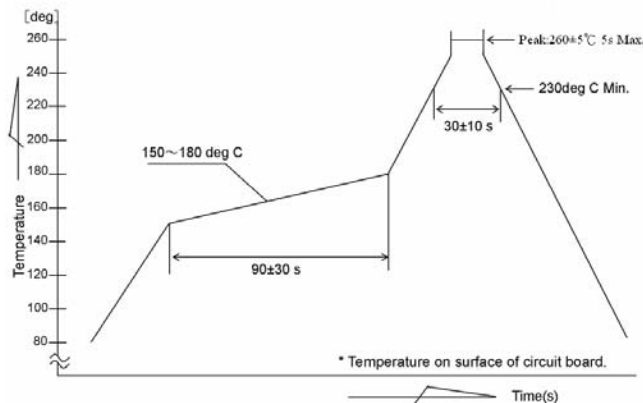
No.	Item	Material
1	Core	Ni-Zn ferrite
2	Wire	Copper Wire
3	Coating	Epoxy with magnetic
4	Solder	Lead free

7. Reliability and Test Condition

Item	Performance	Test Method and Remarks
Operating Temperature	- 25 ~ +125°C.	Including self-generated heat
Storage Temperature	-40 ~ +85°C. - 5 to 40°C for the product with taping.	
Rated current		
Inductance (L)	Within the specified tolerance	LCR Meter: HP 4285A or equivalent, 100kHz, 1V
DC Resistance		DC Ohmmeter: HIOKI3227 or equivalent
Temperature characteristics	Inductance change : Within±20%	Measurement of inductance shall be taken at temperature rang within-25°C to +85°C. With reference to inductance value at+20 °C,change rate shall be calculated. Measurement of inductance shall be taken at temperature rang within-40°C to +125°C. With reference to inductance value at+20 °C,change rate shall be calculated.
Resistance to flexure substrate	No damage.	The test samples shall be soldered to the testing board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2mm.  Substrate size : 100x40x1.0 Substrate material : glass epoxy-resin Solder cream thickness : 0.15 
Adhesion of Terminal electrode	Shall not come off PC board.	The test samples shall be soldered to the testing board and by the reflow.  Applied force : 10 N to X and Y directions. Duration : 5s Solder cream thickness : 0.15

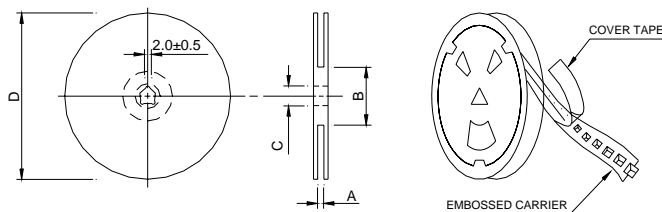
Item	Performance	Test Method and Remarks															
Resistance to Vibration	Inductance change : Within±10% No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions. Frequency: 10-55Hz Total Amplitude: 1.5mm (May not exceed acceleration 196m/S ²) Sweeping Method:10Hz to 55Hz to 10Hz for 1min. Time : 2 hours each in X,Y, and Z Direction. Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.															
Solderability	At least 90% of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below. Flux : methanol solution containing rosin 25% Solder temperature: 245±5°C Time: 5±1.0 sec. Immersion depth: All sides of mounting terminal shall be immersed.															
Resistance to soldering	Inductance change : Within±10% No abnormality observed in appearance.	Test board thickness:1.0mm Test board material:glass epoxy resin THE Chip shall be stabilized normal condition for1~2hours befor measuring  <p style="text-align: center;">Reflow Soldering</p> <p style="text-align: center;">PRE-HEATING SOLDERING NATURAL COOLING</p> <p style="text-align: center;">TP (260°C / 40s max.)</p> <p style="text-align: center;">217 200 150 25</p> <p style="text-align: center;">60-180s 20-40s 60-150s</p> <p style="text-align: center;">480s max.</p> <p style="text-align: center;">TIME (sec.)</p>															
Thermal shock		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown below in sequence. The temperature cycles shall be repeated 100 cycles . <table border="1" data-bbox="1013 1167 1396 1285"> <thead> <tr> <th>Phase</th> <th>Temperature(°C)</th> <th>Time(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55 ±2°C</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Room Temp</td> <td>Within 3</td> </tr> <tr> <td>3</td> <td>85±2°C</td> <td>30±3</td> </tr> <tr> <td>4</td> <td>Room Temp</td> <td>Within 3</td> </tr> </tbody> </table>	Phase	Temperature(°C)	Time(min.)	1	-55 ±2°C	30±3	2	Room Temp	Within 3	3	85±2°C	30±3	4	Room Temp	Within 3
Phase	Temperature(°C)	Time(min.)															
1	-55 ±2°C	30±3															
2	Room Temp	Within 3															
3	85±2°C	30±3															
4	Room Temp	Within 3															
Damp heat life test		Test Method and Remarks The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below. Temperature: 40±2 C Humidity: 90-95%RH Time: 504+/-8 hrs															
Loading under damp heat life test	Inductance change : Within±10% No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below. Temperature: 60±2 C Humidity: 90-95%RH Applied current: Rated current Time: 500+24/-0 hrs															
Low temperature life test		The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below. Temperature:-40±2°C Time: 500±8 hrs.															
Loading at high temperature life test		The test samples shall be soldered to the test board by the reflow. Temperature: 85±2°C . Applied current: Rated current Time: 500±8 hrs.															

8. Soldering



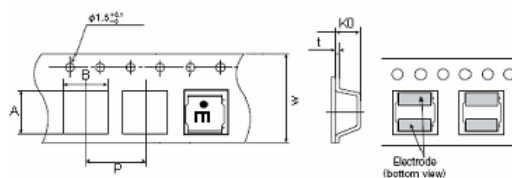
9. Packaging Information

(1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
HPC4018B	13.5±1.0	80±2.0	13±0.5	330±3.0

(2) Tape Dimension



Type	A(mm)	B(mm)	Ko(mm)	P(mm)	W(mm)	t(mm)
HPC4018B	4.3±0.1	4.3±0.1	2.1±0.1	8.0±0.1	12±0.3	0.3±0.1

(3) Packaging Quantity

Type	Chip / Reel
HPC4018B	3500

Application Notice

- Storage Conditions
 - To maintain the solderability of terminal electrodes:
 - 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 - 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
 - 3. Recommended products should be used within 12 months form the time of delivery.
 - 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

測試報告 Test Report

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 (東莞臺慶精密電子有限公司 / TAI-TECH ADVANCED ELECTRONICS (DONGGUAN) CO. LTD.)
 (臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO.
 桃園縣楊梅市幼獅工業區幼四路1之1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI CITY, TAO-YUAN
 HSIEN, TAIWAN R. O. C.)
 (廣東省東莞市黃江鎮黃牛埔福祥街2號 / NO. 2, FUXIANG STREET, HUANGNIUPU, HUANGJIANG TOWN, DONGGUAN, GUANGDONG)
 (江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU,
 CHINA)



以下測試樣品係由客戶送樣，且由客戶聲稱並經客戶確認如下 (The following samples was/were submitted and identified by/on behalf of the client as) :

樣品名稱(Sample Description) : SMD POWER INDUCTOR
 樣品型號(Style/Item No.) : HPC, SPC, UHP, SPC, TLPC, TLPH, SPI SERIES
 收件日期(Sample Receiving Date) : 2013/02/22
 測試期間(Testing Period) : 2013/02/22 TO 2013/03/01

=====
 測試需求(Test Requested) : (1) 依據客戶指定，進行鎘，鉛，汞，六價鉻，多溴聯苯，多溴聯苯醚測試。(As specified by client, to test Cadmium, Lead, Mercury, Cr(VI), PBBs, PBDEs contents in the submitted sample.)
 (2) 依據客戶指定，進行鹵素-氟、氯、溴、碘測試。(As specified by client, to test Halogen-Fluorine, Chlorine, Bromine, Iodine contents in the submitted sample.)
 測試方法(Test Method) : 請見下一頁 (Please refer to next pages).
 測試結果(Test Results) : 請見下一頁 (Please refer to next pages).


 Chenyu Kung / Operation Manager
 Signed for and on behalf of
 SGS TAIWAN LTD.
 Chemical Laboratory - Taipei



測試報告

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測試結果(Test Results)

測試部位(PART NAME) No.1 : 整體混測(5款) (MIXED ALL PARTS(5 TYPES))

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result)
				No.1
鎘 / Cadmium (Cd)	mg/kg	參考IEC 62321: 2008方法, 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
鉛 / Lead (Pb)	mg/kg	參考IEC 62321: 2008方法, 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321: 2008方法, 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	參考IEC 62321: 2008方法, 以UV-VIS檢測. / With reference to IEC 62321: 2008 and performed by UV-VIS.	2	n.d.
鹵素 / Halogen				
鹵素 (氟) / Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	參考BS EN 14582:2007, 以離子層析儀分析. / With reference to BS EN 14582:2007. Analysis was performed by IC.	50	n.d.
鹵素 (氯) / Halogen-Chlorine (Cl) (CAS No.: 22537-15-1)			50	n.d.
鹵素 (溴) / Halogen-Bromine (Br) (CAS No.: 10097-32-2)			50	n.d.
鹵素 (碘) / Halogen-Iodine (I) (CAS No.: 14362-44-8)			50	n.d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
多溴聯苯總和 / Sum of PBBs	mg/kg	參考IEC 62321: 2008方法, 以氣相層析/質譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS.	-	n.d.
一溴聯苯 / Monobromobiphenyl			5	n.d.
二溴聯苯 / Dibromobiphenyl			5	n.d.
三溴聯苯 / Tribromobiphenyl			5	n.d.
四溴聯苯 / Tetrabromobiphenyl			5	n.d.
五溴聯苯 / Pentabromobiphenyl			5	n.d.
六溴聯苯 / Hexabromobiphenyl			5	n.d.
七溴聯苯 / Heptabromobiphenyl			5	n.d.
八溴聯苯 / Octabromobiphenyl			5	n.d.
九溴聯苯 / Nonabromobiphenyl			5	n.d.
十溴聯苯 / Decabromobiphenyl			5	n.d.
多溴聯苯醚總和 / Sum of PBDEs			-	n.d.
一溴聯苯醚 / Monobromodiphenyl ether			5	n.d.
二溴聯苯醚 / Dibromodiphenyl ether			5	n.d.
三溴聯苯醚 / Tribromodiphenyl ether			5	n.d.
四溴聯苯醚 / Tetrabromodiphenyl ether			5	n.d.
五溴聯苯醚 / Pentabromodiphenyl ether			5	n.d.
六溴聯苯醚 / Hexabromodiphenyl ether			5	n.d.
七溴聯苯醚 / Heptabromodiphenyl ether			5	n.d.
八溴聯苯醚 / Octabromodiphenyl ether			5	n.d.
九溴聯苯醚 / Nonabromodiphenyl ether	5	n.d.		
十溴聯苯醚 / Decabromodiphenyl ether	5	n.d.		

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備註(Note) :

1. mg/kg = ppm ; 0.1wt% = 1000ppm
2. n.d. = Not Detected (未檢出)
3. MDL = Method Detection Limit (方法偵測極限值)
4. "-" = Not Regulated (無規格值)
5. 樣品的測試是基於申請人要求混合測試，報告中的混合測試結果不代表其中個別單一材質的含量。
(The samples was/were analyzed on behalf of the applicant as mixing sample in one testing.
The above results was/were only given as the informality value.)

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測試報告 Test Report

號碼(No.) : CE/2013/23406 日期(Date) : 2013/03/01 頁數(Page) : 5 of 8

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO.

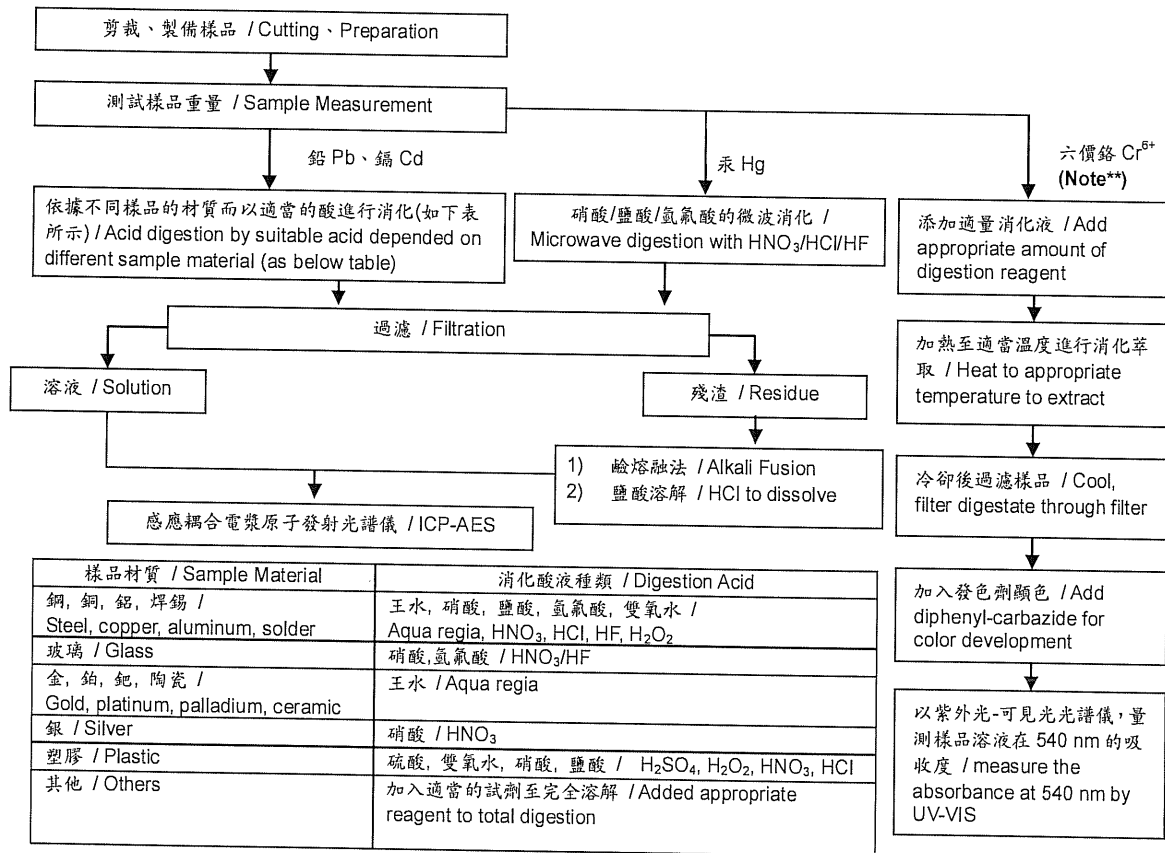
桃園縣楊梅市幼獅工業區幼四路1之1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI CITY, TAO-YUAN HSIEN. TAIWAN R. O. C.)

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- 1) 根據以下的流程圖之條件，樣品已完全溶解。(六價鉻測試方法除外) / These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)
- 2) 測試人員：楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 3) 測試負責人：張啓興 / Name of the person in charge of measurement: Troy Chang



Note**: (1) 針對非金屬材料加入鹼性消化液，加熱至 90~95°C 萃取。 / For non-metallic material, add alkaline digestion reagent and heat to 90~95°C.

(2) 針對金屬材料加入純水，加熱至沸騰萃取。 / For metallic material, add pure water and heat to boiling.



測試報告 Test Report

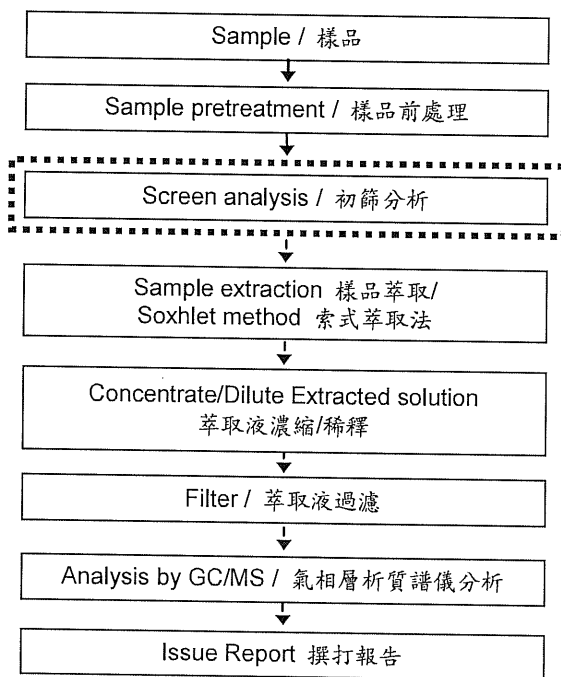
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多溴聯苯/多溴聯苯醚分析流程圖 / PBB/PBDE analytical FLOW CHART

- 測試人員：翁賜彬 / Name of the person who made measurement: Roman Wong
 - 測試負責人：張啓興 / Name of the person in charge of measurement: Troy Chang
- 初次測試程序 / First testing process —————>
- 選擇性篩檢程序 / Optional screen process>
- 確認程序 / Confirmation process - - ->



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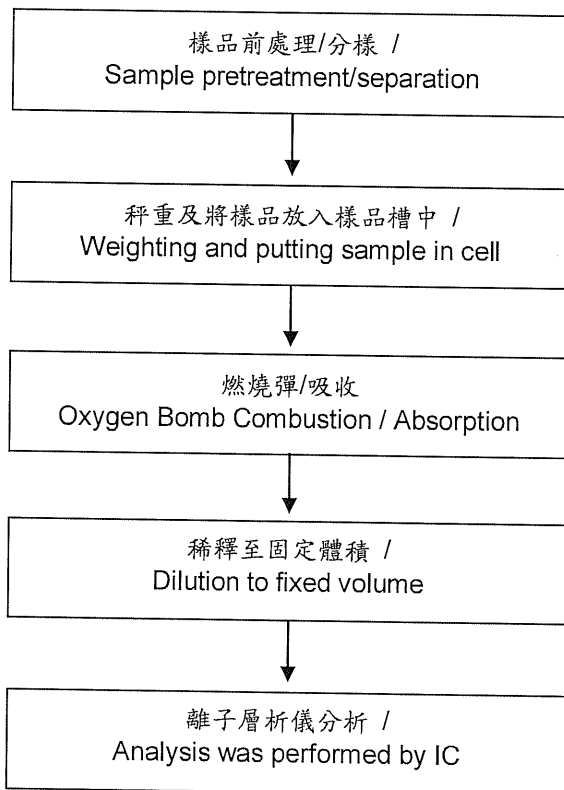
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鹵素分析流程圖 / Analytical flow chart of halogen content

- 測試人員：陳恩臻 / Name of the person who made measurement: Rita Chen
- 測試負責人：張啓興 / Name of the person in charge of measurement: Troy Chang



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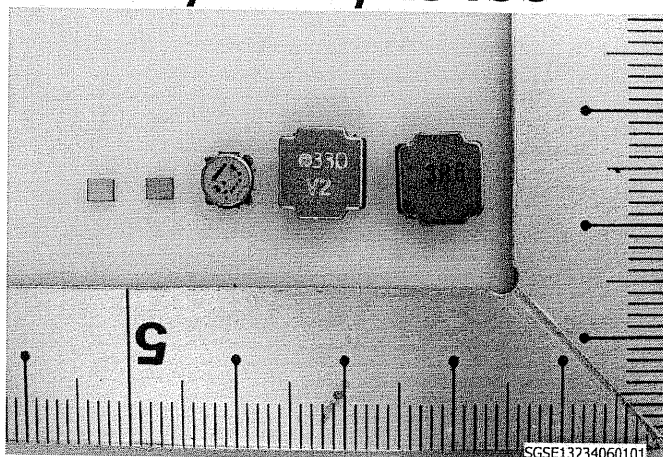
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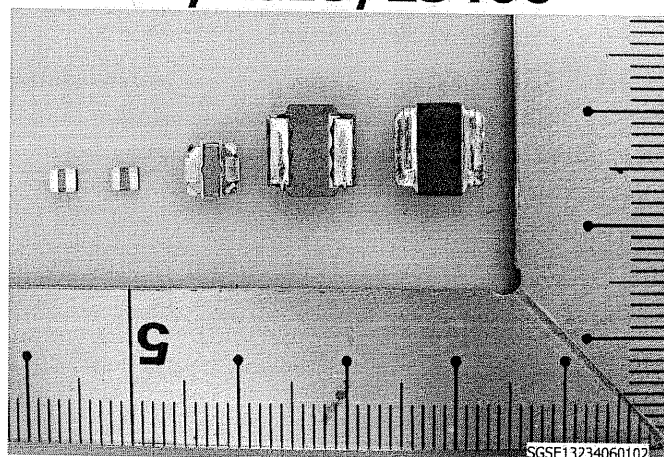


* 照片中如有箭頭標示，則表示為實際檢測之樣品/部位。
 (The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2013/23406



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** 報告結尾(End of Report) **

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